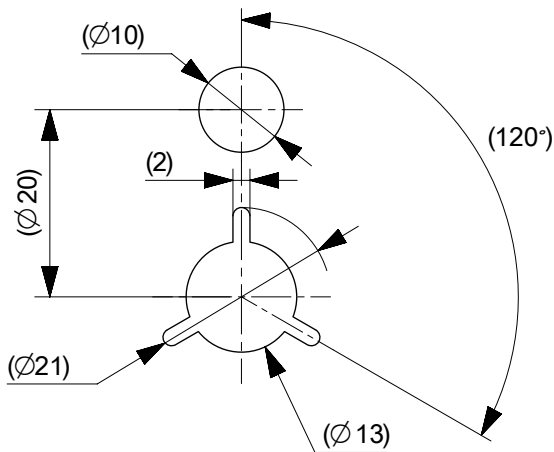
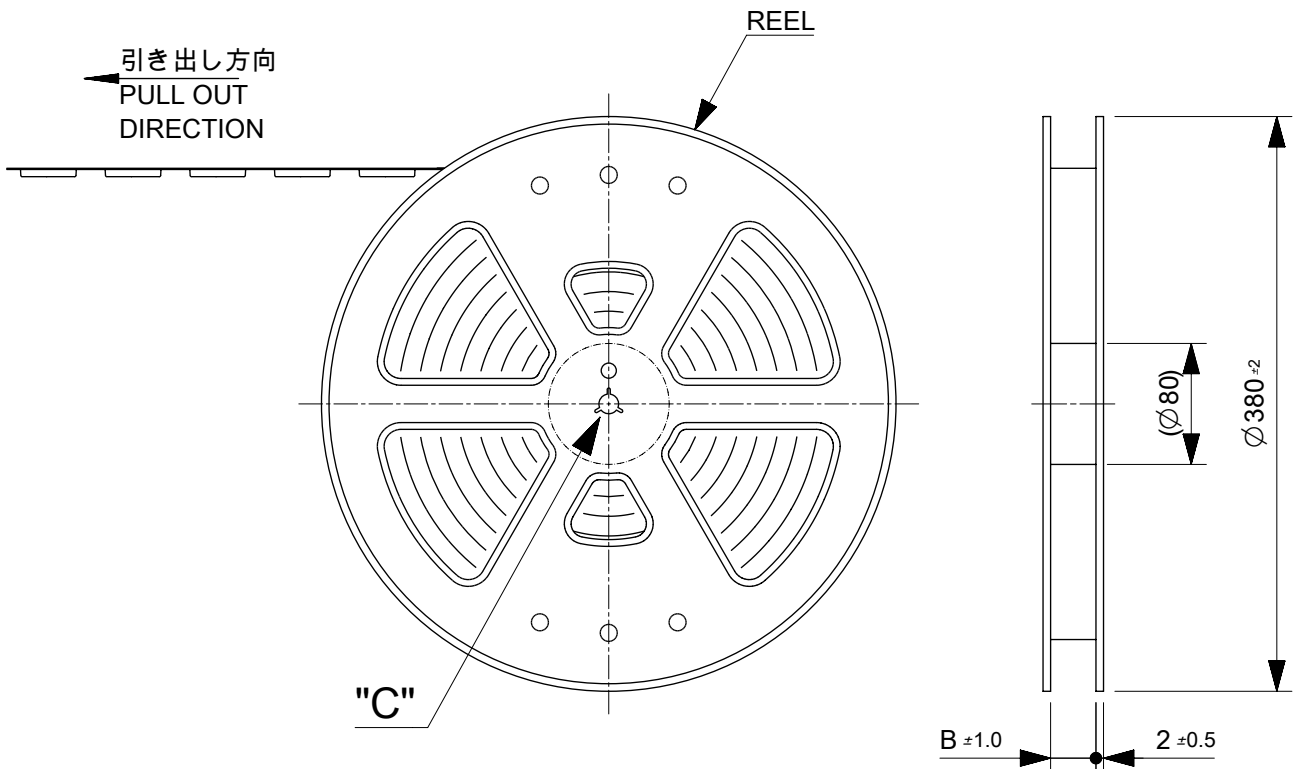
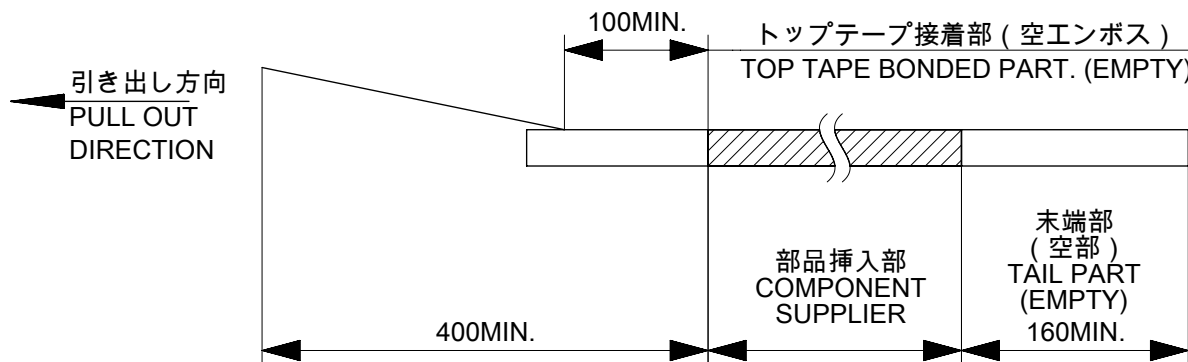




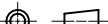
注記 NOTES

- 製品詳細寸法については製品単体図面を参照下さい。
DETAIL DIMENSION, SEE PRODUCT DRAWING
- 梱包数量 : 6000 個 / リール
NUMBER OF CONNECTORS : 6000 PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

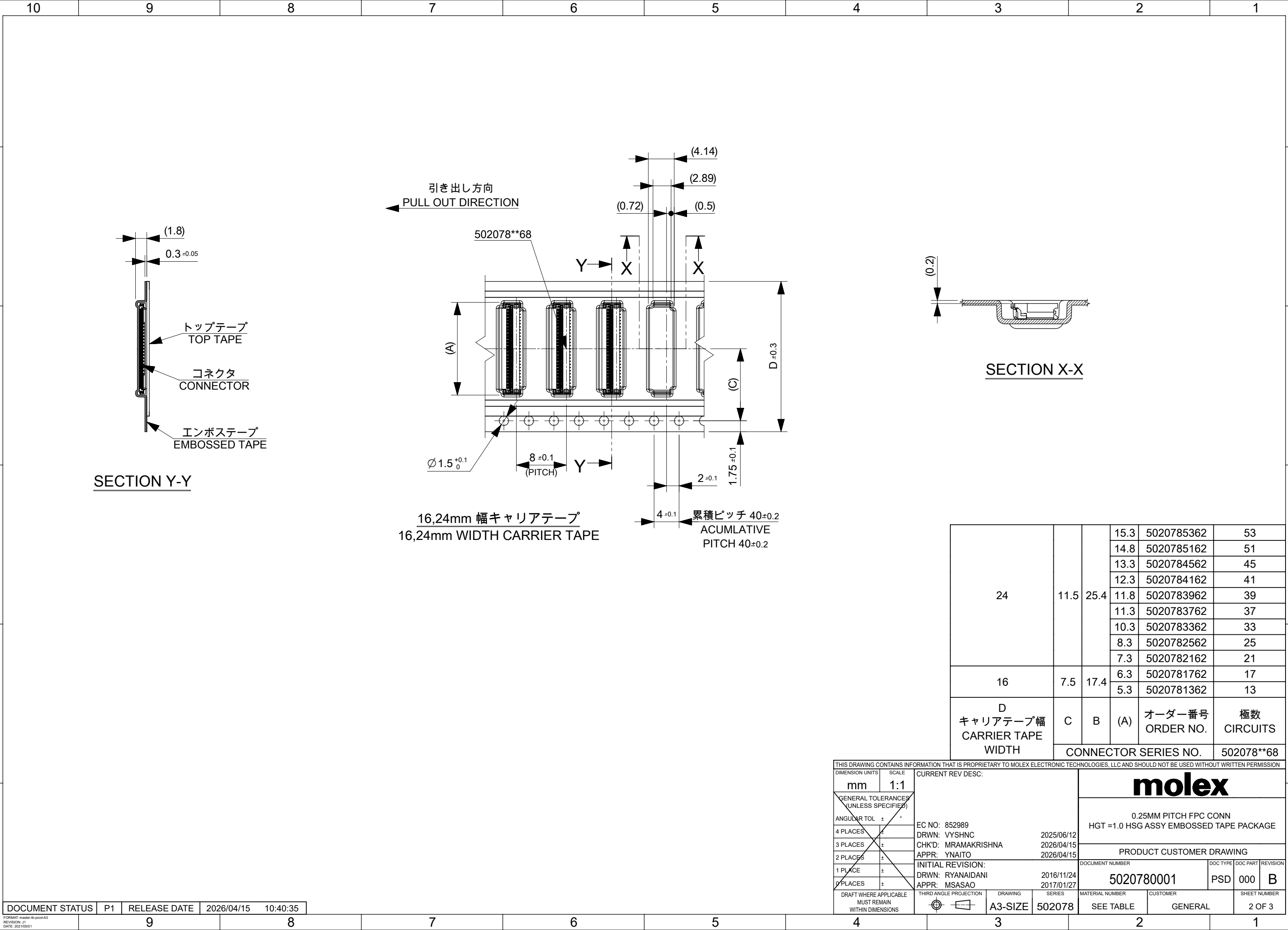


- 材料 MATERIAL
キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYRENE)
トップテープ (TOP TAPE) : PET , PE , PEF
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- カバーテープの剥離強度については、 IEC60286-3 に準拠
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.

CONNECTOR SERIES NO. 502078**68

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											
DIMENSION UNITS		SCALE		CURRENT REV DESC:				molex 0.25MM PITCH FPC CONN HGT =1.0 HSG ASSY EMBOSSED TAPE PACKAGE			
mm		1:1									
GENERAL TOLERANCES (UNLESS SPECIFIED) ANGULAR TOL ± ° 4 PLACES ± 3 PLACES ± 2 PLACES ± 1 PLACE ± 0 PLACES ±				EC NO: 852989							
				DRWN: VYSHNC				2025/06/12			
				CHK'D: MRAMAKRISHNA				2026/04/15			
				APPR: YNAITO				2026/04/15			
				PRODUCT CUSTOMER DRAWING							
				INITIAL REVISION:				DOCUMENT NUMBER		DOC TYPE	DOC PART
DRWN: RYANAIDANI				2016/11/24		5020780001		PSD	000	B	
APPR: MSASAO				2017/01/27							
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION		DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER	SHEET NUMBER
				A3-SIZE		502078		SEE SHEET 2		GENERAL	1 OF 3

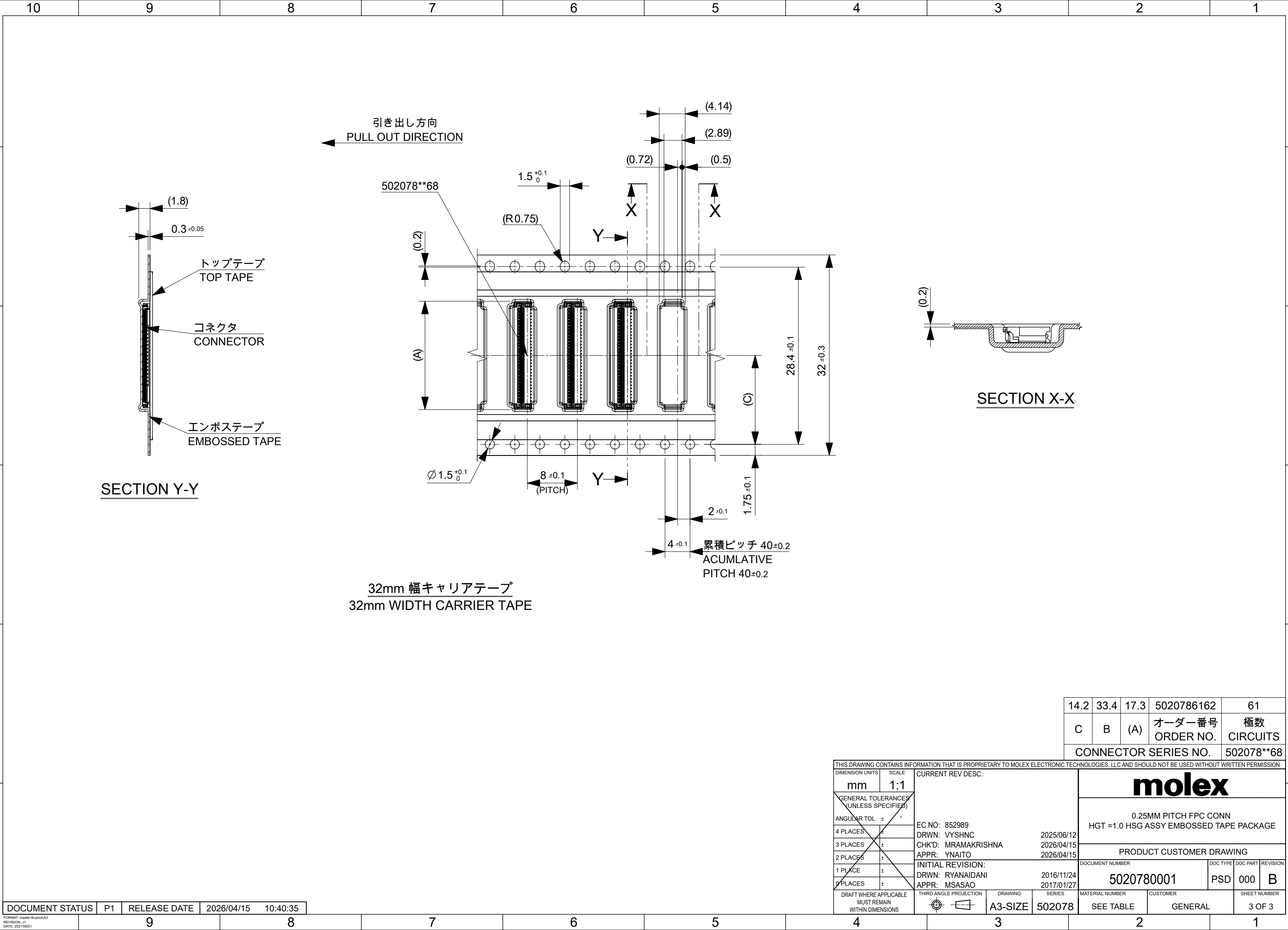
DOCUMENT STATUS	P1	RELEASE DATE	2026/04/15	10:40:35
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DOCUMENT STATUS	P1	RELEASE DATE	2026/04/15	10:40:35
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FORMAT: master-b-prod-A3
REVISION: J1
DATE: 2021/05/01

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION												
DIMENSION UNITS		SCALE		CURRENT REV DESC:		molex						
mm		1:1										
GENERAL TOLERANCES (UNLESS SPECIFIED) ANGULAR TOL ± ° 4 PLACES ± 3 PLACES ± 2 PLACES ± 1 PLACE ± 0 PLACES ± DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				EC NO: 852989		0.25MM PITCH FPC CONN HGT =1.0 HSG ASSY EMBOSSED TAPE PACKAGE						
				DRWN: VYSHNC						2025/06/12		
				CHK'D: MRAMAKRISHNA						2026/04/15		
				APPR: YNAITO		2026/04/15		PRODUCT CUSTOMER DRAWING				
				INITIAL REVISION:				DOCUMENT NUMBER		DOC TYPE	DOC PART	REVISION
				DRWN: RYANAIDANI		2016/11/24		5020780001		PSD	000	B
APPR: MSASAO		2017/01/27										
THIRD ANGLE PROJECTION		DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER	SHEET NUMBER			
		A3-SIZE		502078		SEE TABLE		GENERAL	2 OF 3			

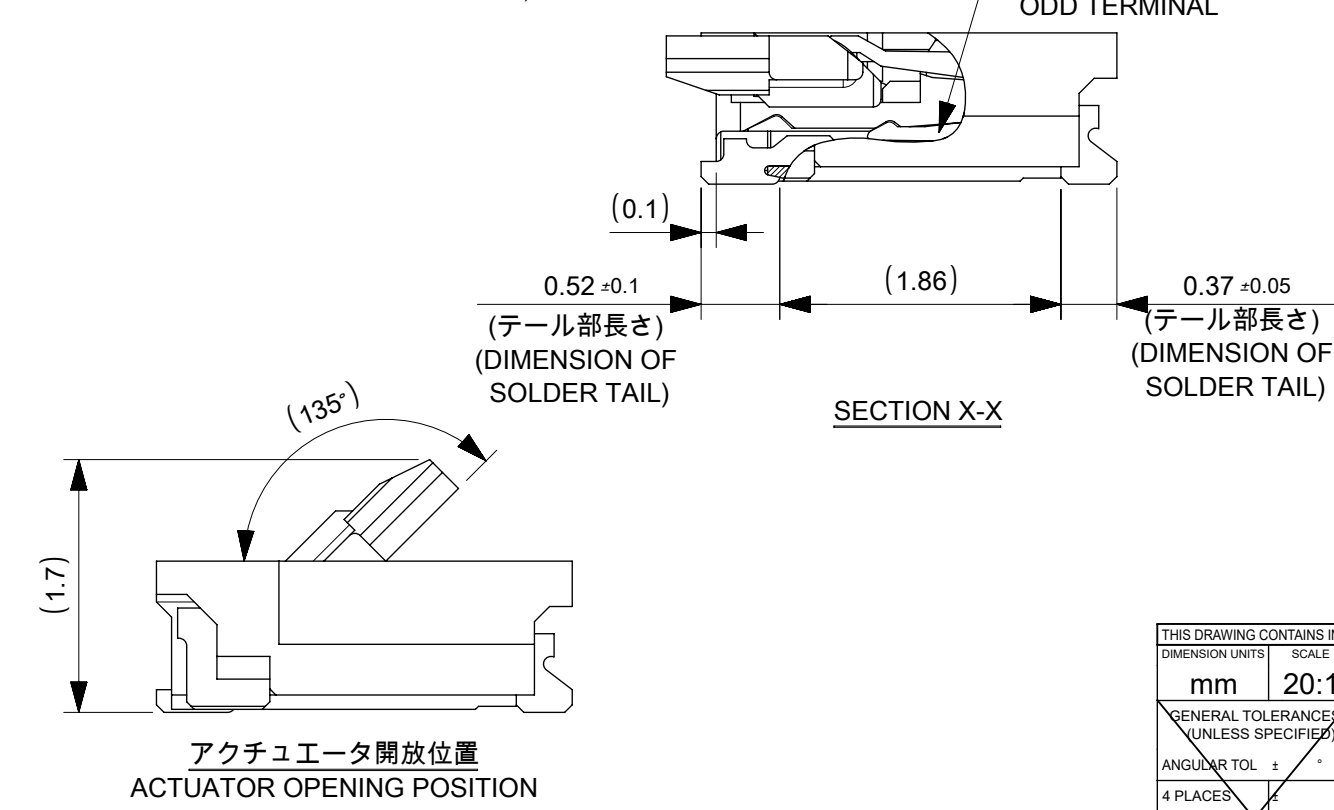
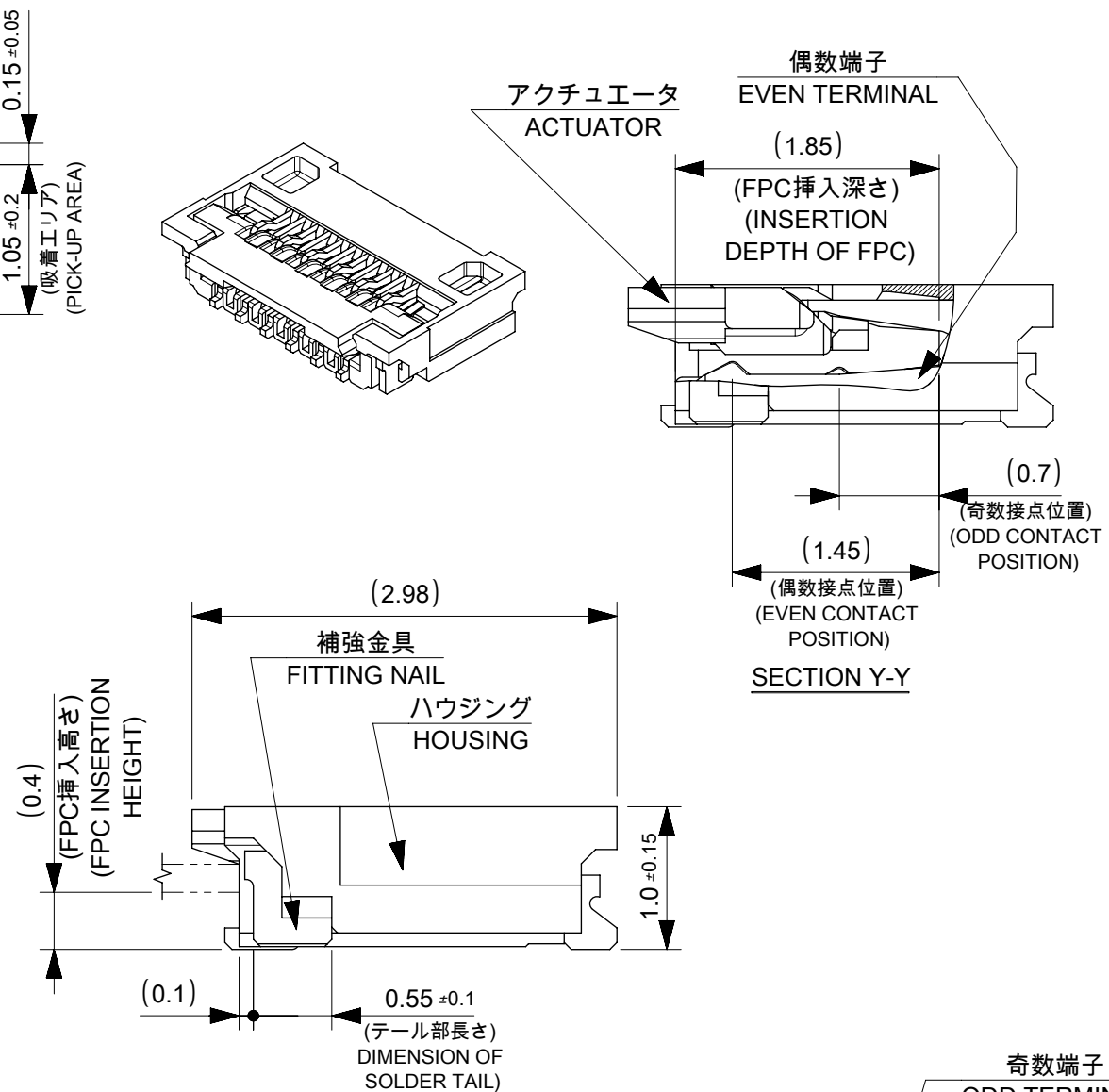
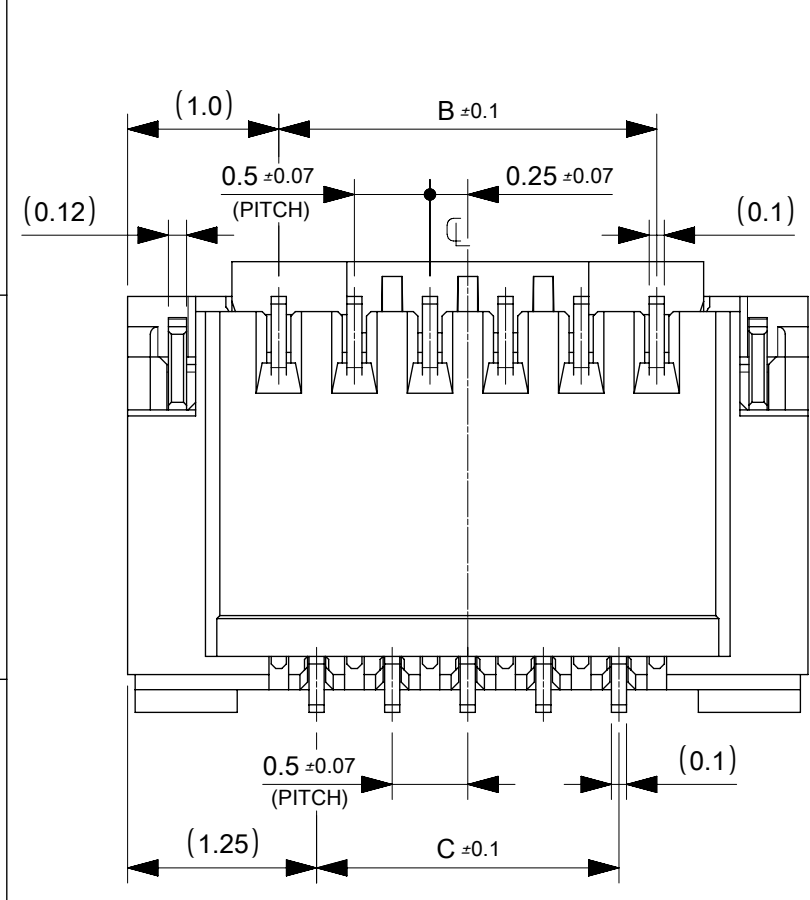
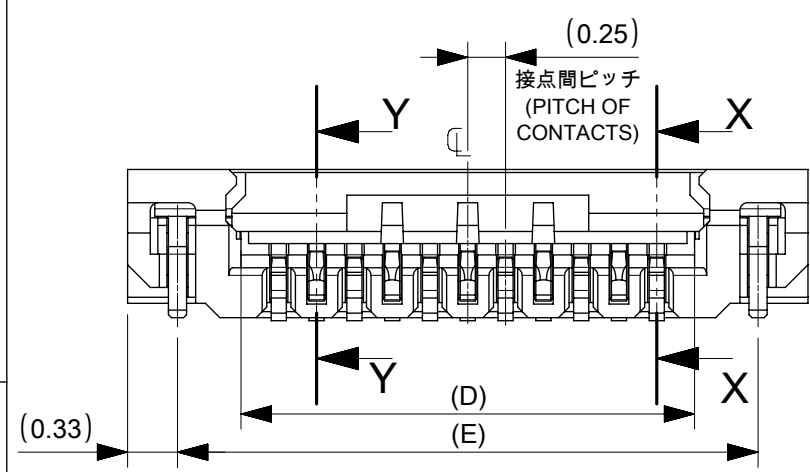
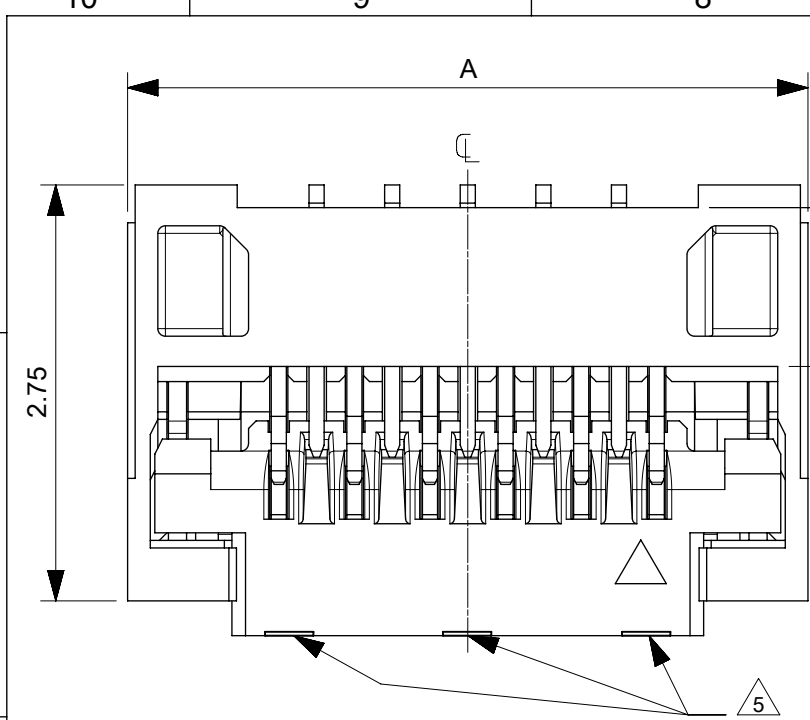


14.2	33.4	17.3	5020786162	61
C	B	(A)	オーダー番号 ORDER NO.	極数 CIRCUITS
CONNECTOR SERIES NO.			502078**68	

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																	
DIMENSION UNITS		SCALE		CURRENT REV DESC:			molex										
mm		1:1															
GENERAL TOLERANCES (UNLESS SPECIFIED)				EC NO: 852989 DRWN: VYSHNC 2025/06/12 CHK'D: MRAMAKRISHNA 2026/04/15 APPR: YNAITO 2026/04/15			0.25MM PITCH FPC CONN HGT =1.0 HSG ASSY EMBOSSSED TAPE PACKAGE										
ANGULAR TOL ± °																	
4 PLACES		±															
3 PLACES		±															
2 PLACES		±															
1 PLACE		±		INITIAL REVISION: DRWN: RYANAIDANI 2016/11/24 APPR: MSASAO 2017/01/27			PRODUCT CUSTOMER DRAWING										
0 PLACES		±															
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION		DRAWING		SERIES		DOCUMENT NUMBER		DOC TYPE		DOC PART		REVISION	
						A3-SIZE		502078		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER			
								SEE TABLE		GENERAL		3 OF 3					

DOCUMENT STATUS	P1	RELEASE DATE	2026/04/15	10:40:35
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FORMAT: master-b-prod-A3
REVISION: J1
DATE: 2021/05/01



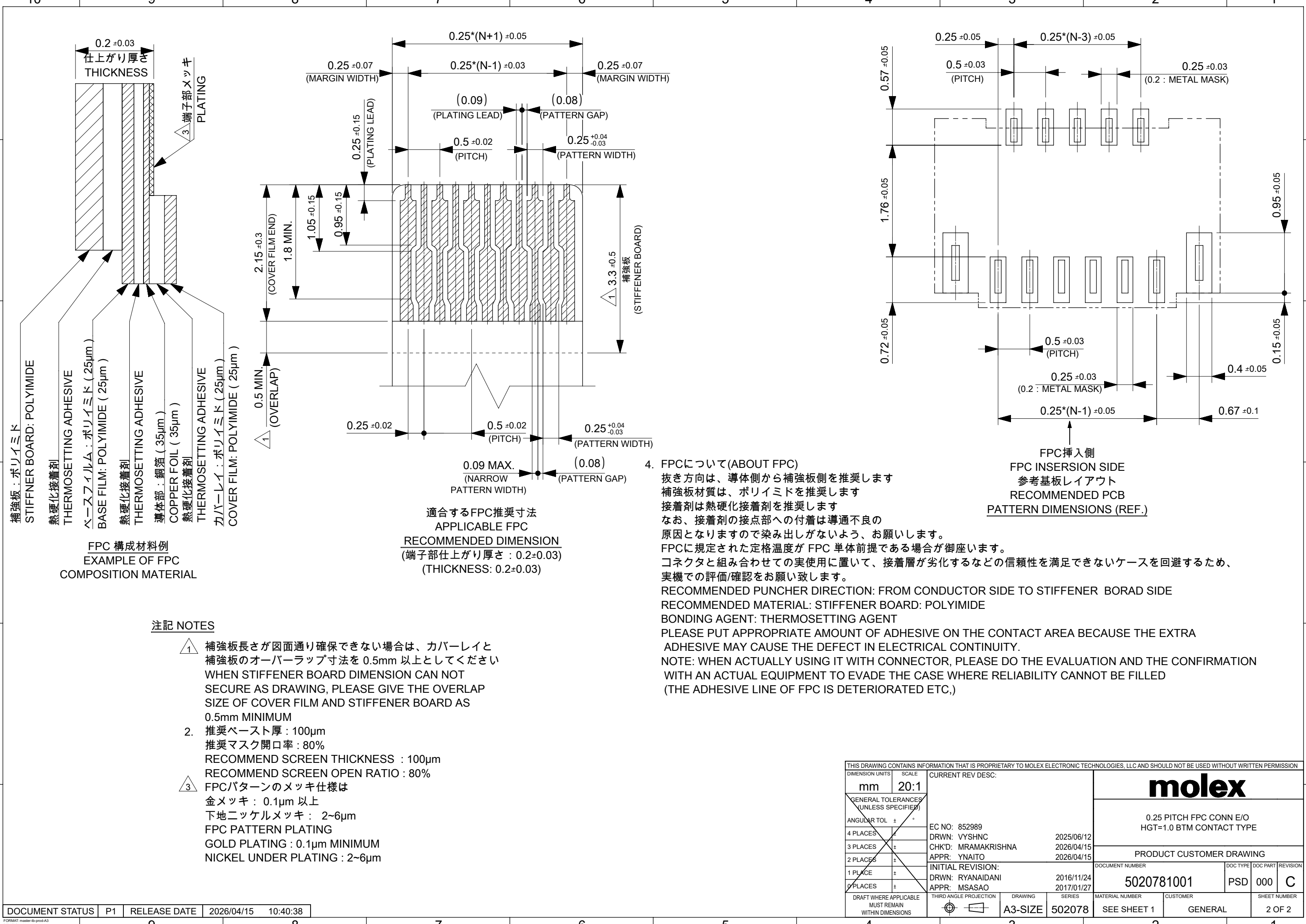
注記 NOTES

1. 使用材料 MATERIALS
ハウジング : 液晶ポリマー(UL94V-0 、ベージュ)
アクチュエータ : ポリアミド(UL94HB 、黒色)
端子 : リン青銅
補強金具 : リン青銅
HOUSING : LCP (BEIGE)
ACTUATOR : PA (BLACK)
TERMINAL : PHOSPHOR BRONZE
FITTING NAIL : PHOSPHOR BRONZE
2. メッキ仕様 PLATING
端子 TERMINAL
接点部 : 金メッキ0.1 μm以上
テール部 : 金メッキ
下地 : ニッケルメッキ1.0 μm以上
CONTACT AREA : Gold PLATING 0.1μm MINIMUM
TAIL AREA : Gold PLATING
UNDER PLATING : Nickel PLATING 1.0μm MINIMUM
金具 FITTING NAIL
表面 : スズメッキ 1.0 μm以上
下地 : ニッケルメッキ1.0 μm以上
ALL OVER : Tin PLATING 1.0μm MINIMUM
UNDER PLATING : Nickel PLATING 1.0μm MINIMUM
3. 端子、補強金具のコプラナリティーは0.1以下とする
COPLANALITY OF SOLDER TAILS AND FITTING NAILS : 0.1MAX.
4. 一般公差 : ± 0.3
GENERAL TOLERANCES: ±0.3
5. アクチュエータの図示箇所にゲート逃げの凹みがつきます
(極数により、レイアウトが異なります)
THERE ARE DENT SHAPES AT ACTUATOR FOR MOLDING GATE
(LAYOUT DIFFER ACCORDING TO CIRCUIT NUMBER)
6. 塩素系・臭素系難燃剤非使用
CHLORINATED AND BROMINATED FLAME RETARDANTS FREE

16.34	15.5	14.5	15	17	5020786162	5020786168	61
14.34	13.5	12.5	13	15	5020785362	5020785368	53
13.84	13	12	12.5	14.5	5020785162	5020785168	51
12.34	11.5	10.5	11	13	5020784562	5020784568	45
11.34	10.5	9.5	10	12	5020784162	5020784168	41
10.84	10	9	9.5	11.5	5020783962	5020783968	39
10.34	9.5	8.5	9	11	5020783762	5020783768	37
9.34	8.5	7.5	8	10	5020783362	5020783368	33
7.34	6.5	5.5	6	8	5020782562	5020782568	25
6.34	5.5	4.5	5	7	5020782162	5020782168	21
5.34	4.5	3.5	4	6	5020781762	5020781768	17
4.34	3.5	2.5	3	5	5020781362	5020781368	13
E	D	C	B	A	ORDER No.	MATERIAL No.	CIRCUIT =N

CONNECTOR SERIES No. 502078**68

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DIMENSION UNITS mm		SCALE 20:1	
CURRENT REV DESC:			
molex			
0.25 PITCH FPC CONN E/O HGT=1.0 BTM CONTACT TYPE			
PRODUCT CUSTOMER DRAWING			
EC NO: 852989 DRWN: VYSHNC CHK'D: MRAMAKRISHNA APPR: YNAITO		2025/06/12 2026/04/15 2026/04/15	
INITIAL REVISION: DRWN: RYANAIDANI APPR: MSASAO		2016/11/24 2017/01/27	
DOCUMENT NUMBER 5020781001		DOC TYPE PSD	
CUSTOMER GENERAL		SHEET NUMBER 1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION DRAWING A3-SIZE	
SERIES 502078		MATERIAL NUMBER SEE TABLE	



補強板：ポリイミド
STIFFENER BOARD: POLYIMIDE
熱硬化接着剤
THERMOSETTING ADHESIVE
ベースフィルム：ポリイミド (25μm)
BASE FILM: POLYIMIDE (25μm)
熱硬化接着剤
THERMOSETTING ADHESIVE
導体部：銅箔 (35μm)
COPPER FOIL (35μm)
熱硬化接着剤
THERMOSETTING ADHESIVE
カバーレイ：ポリイミド (25μm)
COVER FILM: POLYIMIDE (25μm)

FPC 構成材料例
EXAMPLE OF FPC
COMPOSITION MATERIAL

適合するFPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(端子部仕上がり厚さ：0.2±0.03)
(THICKNESS: 0.2±0.03)

- 注記 NOTES
- 1. 補強板長さが図面通り確保できない場合は、カバーレイと補強板のオーバーラップ寸法を 0.5mm 以上としてください
WHEN STIFFENER BOARD DIMENSION CAN NOT SECURE AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM
 - 2. 推奨ペースト厚：100μm
推奨マスク開口率：80%
RECOMMEND SCREEN THICKNESS：100μm
RECOMMEND SCREEN OPEN RATIO：80%
 - 3. FPCパターンのメッキ仕様は
金メッキ：0.1μm 以上
下地ニッケルメッキ：2~6μm
FPC PATTERN PLATING
GOLD PLATING：0.1μm MINIMUM
NICKEL UNDER PLATING：2~6μm

4. FPCについて(ABOUT FPC)
抜き方向は、導体側から補強板側を推奨します
補強板材質は、ポリイミドを推奨します
接着剤は熱硬化接着剤を推奨します
なお、接着剤の接点部への付着は導通不良の原因となりますので染み出しがないよう、お願いします。
FPCに規定された定格温度が FPC 単体前提である場合が御座います。
コネクタと組み合わせての実使用に置いて、接着層が劣化するなどの信頼性を満足できないケースを回避するため、実機での評価/確認をお願い致します。
RECOMMENDED PUNCHER DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER BORAD SIDE
RECOMMENDED MATERIAL: STIFFENER BOARD: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY.
NOTE: WHEN ACTUALLY USING IT WITH CONNECTOR, PLEASE DO THE EVALUATION AND THE CONFIRMATION WITH AN ACTUAL EQUIPMENT TO EVADE THE CASE WHERE RELIABILITY CANNOT BE FILLED (THE ADHESIVE LINE OF FPC IS DETERIORATED ETC,)